

***Please replace the abstract with the following amended abstract:***

~~The present invention provides a~~ A semiconductor device comprising includes a die pad section [(200)], a first semiconductor chip [(4)] having a surface [(41)] formed with a first electrode section [(47)] and a back surface [(42)] fixed to the die pad section [(200)] , a second semiconductor chip [(5)] having a surface [(51)] formed with a second electrode section [(57)] and a back surface [(52)] fixed to the surface [(41)] of the first semiconductor chip [(4)], a support member [(300)] having a surface [(301)] fixed to the back surface of the second semiconductor chip [(5)] and a back surface [(302)] fixed to the die pad section [(200)], lead terminal sections (240, 220) respectively electrically connected to the first and second electrode sections (47, 57), and a resin encapsulating body [(10)] that seals the die pad section [(200)], the first and second semiconductor chips (4, 5) and the support member [(300)].